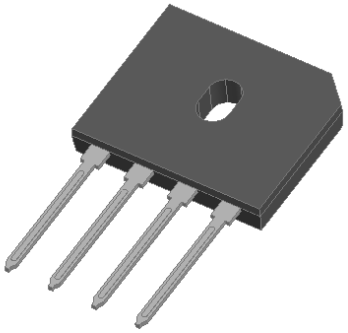
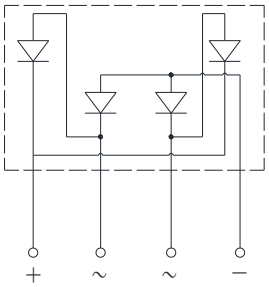
Low VF Bridge Rectifiers





Features

- Glass passivated chip junction
- Ideal for printed circuit boards
- High surge current capability
- Low VF
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.

Mechanical Data

- **Package**: GBU
  Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked on body

■Maximum Ratings (T_a=25℃ Unless otherwise specified)

PARAMETER		SYMBOL	UNIT	GBUL2508
Device marking code				GBUL2508
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	V	800
Maximum RMS Voltage		V_{RMS}	V	560
Maximum DC blocking Voltage		V_{DC}	V	800
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =125℃	I_O	A	25.0
	Without heatsink Ta =25℃			4.0
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25℃		I_{FSM}	A	450
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25℃				900
Current squared time @1ms≤t≤8.3ms Tj=25℃, Rating of per diode		I^2t	A^2S	840
Storage temperature		T_{stg}	℃	-55 ~ +150
Junction temperature		Tj	℃	-55 ~ +150
Dielectric strength @ terminals to case, AC 1 minute		V_{dis}	KV	2.5
Mounting torque @recommend torque：5kg·cm		T_{or}	kg·cm	8.0

■Electrical Characteristics（T_a=25℃ Unless otherwise specified）

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max
Instantaneous forward voltage drop per diode	V_F	V	I_{FM}=12.5A	0.80	0.90	0.92
DC reverse current at rated DC blocking voltage per diode	I_R	μA	T_j=25℃	-	0.16	5
			T_j=125℃	-	55	100
Junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	85	170	350

■Thermal Characteristics （T_a=25℃ Unless otherwise specified）

PARAMETER		SYMBOL	UNIT	GBUL2508
Thermal Resistance	Between junction and ambient, Without heatsink	$R_{\theta J-A}$	℃/W	25.0
	Between junction and Lead, With heatsink	$R_{\theta J-L}$		3.0
	Between junction and Case, With heatsink	$R_{\theta J-C}$		0.5

Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GBUL2508	B1	Approximate 3.96	20	1000	2000	TUBE

■ Characteristics(Typical)

FIG1:Io-Tc Curve

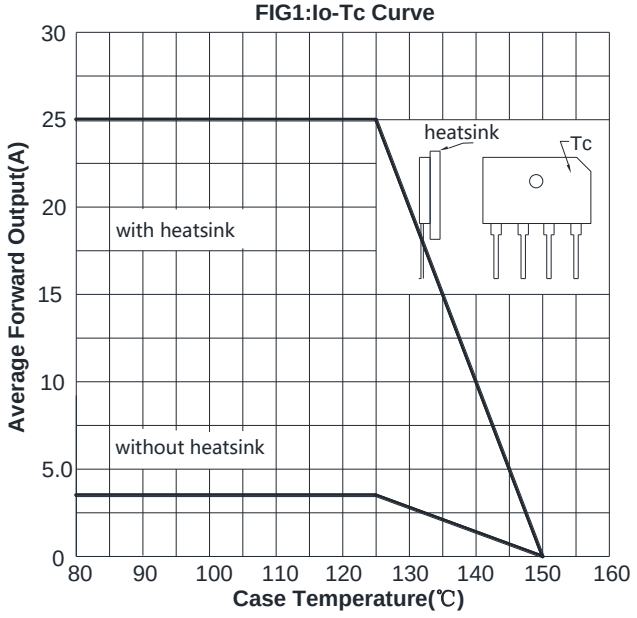


FIG2:Surge Forward Current Capability

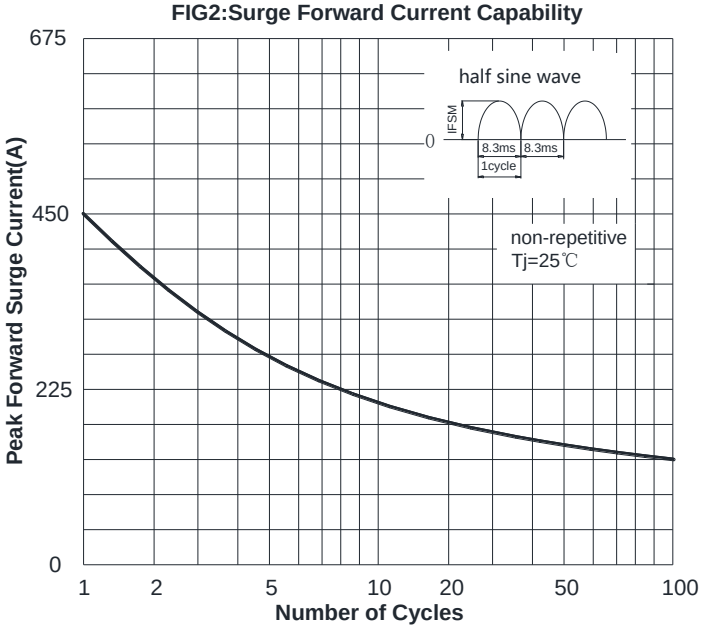


FIG3: Typical Forward Voltage

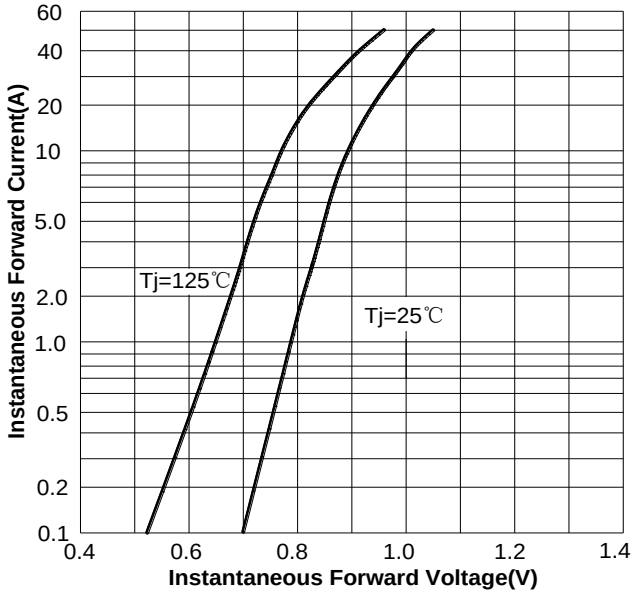
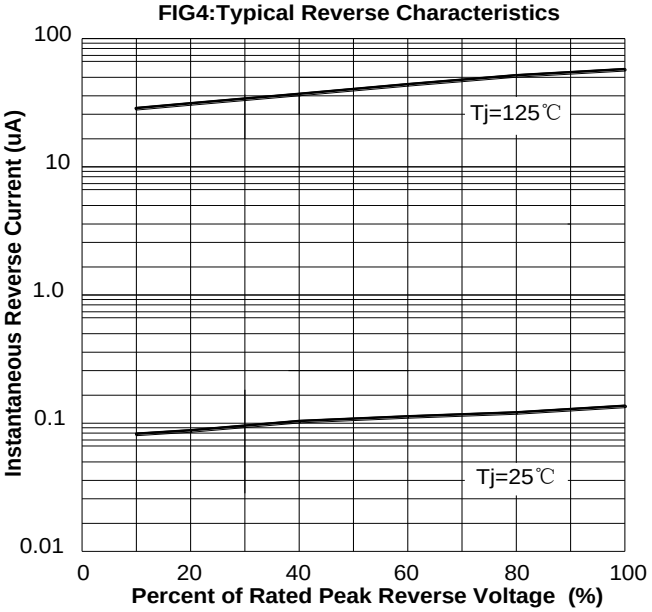
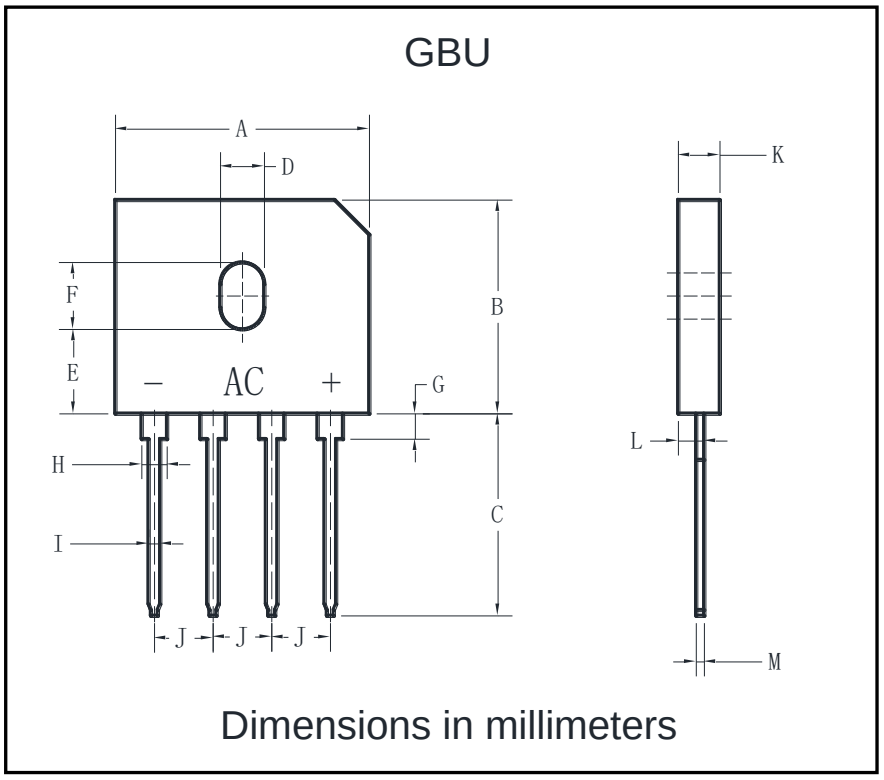


FIG4:Typical Reverse Characteristics



■ Outline Dimensions



GBU		
Dim	Min	Max
A	21.80	22.30
B	18.30	18.80
C	17.50	18.00
D	3.30	3.90
E	7.10	7.50
F	5.50	5.90
G	1.91	2.54
H	2.06	2.54
I	1.02	1.27
J	4.83	5.33
K	3.30	3.56
L	2.40	2.66
M	0.46	0.56

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